

TGVi

- Through Glass Vias (TGV) formation allows to use glass as substrate for 3D integration for applications like RF modules and sensor packaging.

TGVi® expects TGV substrate in the use of 3D integration for semiconductor packaging, and other wide variety of fields.

Glass material	Boro 33, D263, AS87, Eagle XG, Quartz....
Size	Wafer: ϕ 100mm, ϕ 150mm, ϕ 200mm
Thickness	0.3mmT ~ 1mmT
Hole type	Through via, Blind via
Hole shape	Straight
Hole diameter	Φ 25mm ~
Pitch	Min. hole dia x 2

